



H I G H L Y A C C E L E R A T E D T H E R M A L S H O C K

TKLab *provides*

Highly Accelerated Thermal Shock (HATS™)

Tests for Europe and the Middle East





Integrated Reliability Test Systems, Inc.

- Partnership between Conductor Analysis Technologies (Albuquerque, NM) and Microtek Labs (Anaheim, CA)
- Global provider of thermal shock test systems and services to the printed circuit board and electronic interconnect industries
- Products and services provide quantitative data on electrical interconnect reliability

History of Thermal Shock

- MIL-STD-202G, Method 107G
 - Originated in the late 1950's
 - Last updated in 1984
- Cycle time is conservatively estimated based upon mass of samples
- IPC, JEDEC, Delphi and many others have customized this method for their needs

Air-to-Air Systems

- Use “air” as heat transfer mechanism
- Low heat transfer rate to samples
- Lots of thermal mass in transfer cage
- Difficult sample fixturing and wiring
 - Generally infrequent data sampling
- Significant disadvantages in cost and time
 - Electricity and/or liquid nitrogen
 - Long cycle times due to thermal mass

IPC-TM-650, Method 2.6.7.2B (May 2004)

- Thermal shock, continuity and microsection of printed boards

Step	Test Condition A		Test Condition B		Test Condition C	
	Temperature °C [°F]	Time (min) ¹	Temperature °C [°F]	Time (min) ¹	Temperature °C [°F]	Time (min) ¹
1	0, +0/-5 [32, +0/-9]	15	-40, +0/-5 [-40, +0/-9]	15	-55, +0/-5 [-67, +0/-9]	15
2	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0
3	+70, +5/-0 [158, +9/-0]	15	+85, +5/-0 [185, +9/-0]	15	+105, +5/-0 [221, +9/-0]	15
4	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0
Step	Test Condition D		Test Condition E		Test Condition F	
	Temperature °C [°F]	Time (min) ¹	Temperature °C [°F]	Time (min) ¹	Temperature °C [°F]	Time (min) ¹
1	-55, +0/-5 [-67, +0/-9]	15	-65, +0/-5 [-85, +0/-9]	15	-65, +0/-5 [-85, +0/-9]	15
2	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0
3	+125, +5/-0 [257, +9/-0]	15	+150, +5/-0 [302, +9/-0]	15	+170, +5/-0 [338, +9/-0]	15
4	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0	25, +10/-5 [77, +18/-9]	0

¹Or until samples reach test temperature.

- Via net resistance change after 100 cycles
- Or, As Agreed Between User and Supplier (AABUS)

Liquid-to-Liquid Systems

- Use “liquids” as heat transfer mechanism
- High heat transfer rate to samples
- Difficult to move samples between liquids
- Difficult sample fixturing and wiring
 - Generally infrequent data sampling
- Significant disadvantages in cost
 - Liquids are volatile and very expensive

Current Induced Methods

- Apply DC current to internal interconnect to generate heat in the coupons
- Monitor and control resistance/temperature through PTH interconnect
- Typical cycle from room temperature to 150C (delta T of only 125C)
- Limited number of samples per load



HATS™ System

- Air-to-air methodology
 - Single chamber with stationary coupons
 - High volume airflow with large heat transfer capacity
- 36 coupons (144 nets) per chamber load
- Temperature cycles from -55 to +160C
 - Performs traditional air-to-air tests
 - Can emulate current induced cycles
- Software optimized cycle times
- Easy coupon design

Specifications

- Air transfer subsystem
 - Temperature range: -55 to +160C
 - Air transition time: 30 seconds (-55 to +160C)
 - Air Stability: $\pm 2C$
- Data acquisition subsystem
 - Mode: 4-wire resistance
 - Accuracy: 2% of resistance value
 - Precision: 2% resistance CoV
 - Speed: 12 readings per second

HATS™ System





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